



SHINKAWA LTD.

News Release

October 22 2018

Shinkawa to Release New Wire Bonders UTC-5000Super and UTC-5000NeoCu Super

Shinkawa Ltd. (President: Takashi Nagano, Shinjuku-ku, Tokyo) has developed the latest versions of our leading products, wire bonders UTC-5000Super and UTC-5000NeoCu Super and started accepting orders.

<Features of UTC-5000Super/UTC-5000NeoCu Super>

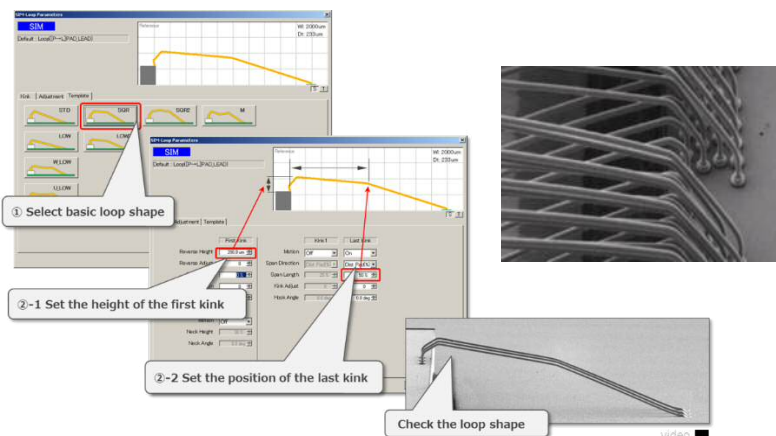
High-speed wire bonder with new SimLoop function as standard-capability

- Optimizing loop shapes automatically by newly developed loop shaping engine
- Enabling intuitive loop shape adjustment with loop display function
- Significantly reducing parameter setup time using loop templates
- Improving UPH by about 7% with built-in overdrive function (*)

Two easy steps to form ideal loops

- Step 1 Select a desired loop shape (template)
Step 2 Set the basic loop dimensions

Shinkawa Loop Shaping Engine automatically selects the parameters to form a loop, reducing parameter adjustment time significantly.



* Depending on device conditions

The SimLoop kit, which enables the SimLoop function on existing equipment (UTC-5000 and UTC-5000 NeoCu), will be released at the same time.

The wire bonder "UTC-5000 NeoCu Super" will be exhibited at SEMICON Japan 2018 from 12 to 14 December 2018.

SEMICON Japan 2018 (at Tokyo Big Sight), Booth No. 1206

- Other Product Line-ups
Die Bonders, Bump Bonders, Flip Chip Bonders, and Package, Package Sorter
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